8-Bit Serial or Parallel-Input/ Serial-Output Shift Register High-Performance Silicon-Gate CMOS

The MC74HC165A is identical in pinout to the LS165. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

This device is an 8-bit shift register with complementary outputs from the last stage. Data may be loaded into the register either in parallel or in serial form. When the Serial Shift/Parallel Load input is low, the data is loaded asynchronously in parallel. When the Serial Shift/Parallel Load input is high, the data is loaded serially on the rising edge of either Clock or Clock Inhibit (see the Function Table).

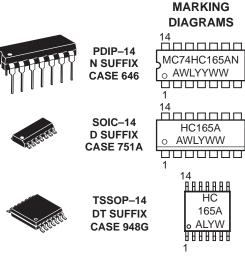
The 2-input NOR clock may be used either by combining two independent clock sources or by designating one of the clock inputs to act as a clock inhibit.

- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2 to 6 V
- Low Input Current: 1 μA
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the Requirements Defined by JEDEC Standard No. 7A
- Chip Complexity: 286 FETs or 71.5 Equivalent Gates



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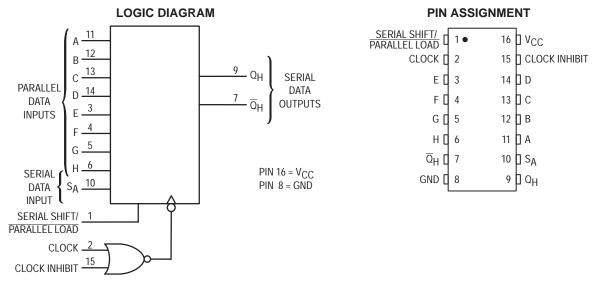


A = Assembly Location

WL or L = Wafer Lot YY or Y = Year WW or W = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC74HC165AN	PDIP-14	2000 / Box
MC74HC165AD	SOIC-14	55 / Rail
MC74HC165ADR2	SOIC-14	2500 / Reel
MC74HC165ADT	TSSOP-14	96 / Rail
MC74HC165ADTR2	TSSOP-14	2500 / Reel



FUNCTION TABLE

Inputs			Internal	Stages	Output			
Serial Shift/ Parallel Load	Clock	Clock Inhibit	SA	A – H	QA	QB	Q _H	Operation
L	Х	Х	Х	a h	а	b	h	Asynchronous Parallel Load
H H	\sum_	L L	L H	X X	L H	Q _{An} Q _{An}	Q _{Gn} Q _{Gn}	Serial Shift via Clock
H H	L L	7	L H	X	L H	Q _{An} Q _{An}	Q _{Gn} Q _{Gn}	Serial Shift via Clock Inhibit
H H	X H	H X	X X	X X	No Change			Inhibited Clock
Н	L	L	Х	Х		No Change		No Clock

X = don't care $Q_{An} - Q_{Gn} = Data shifted from the preceding stage$

MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
VCC	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V
V _{in}	DC Input Voltage (Referenced to GND)	-0.5 to V _{CC} + 0.5	V
V _{out}	DC Output Voltage (Referenced to GND)	-0.5 to V _{CC} + 0.5	V
l _{in}	DC Input Current, per Pin	± 20	mA
l _{out}	DC Output Current, per Pin	± 25	mA
ICC	DC Supply Current, V _{CC} and GND Pins	± 50	mA
PD	Power Dissipation in Still Air Plastic DIP† SOIC Package† TSSOP Package†	750 500 450	mW
T _{stg}	Storage Temperature	- 65 to + 150	°C
TL	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP, SOIC or TSSOP Package)	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range GND \leq (V_{in} or V_{out}) \leq V_{CC} .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Functional operation should be restricted to the Recommended Operating Conditions.

†Derating — Plastic DIP: – 10 mW/°C from 65° to 125°C

SOIC Package: – 7 mW/°C from 65° to 125°C

TSSOP Package: - 6.1 mW/°C from 65° to 125°C

For high frequency or heavy load considerations, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
VCC	DC Supply Voltage (Referenced to GND)			6.0	V
V _{in} , V _{out}	DC Input Voltage, Output Voltage (Referenced to GND)			VCC	V
TA	Operating Temperature, All Package Types	Operating Temperature, All Package Types			°C
t _r , t _f	(Figure 1) V	CC = 2.0 V CC = 3.0 V CC = 4.5 V CC = 6.0 V	0 0 0	1000 600 500 400	ns

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

				Guaranteed Limit			
Symbol	Parameter	Test Conditions	V _{CC}	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
VIH	Minimum High–Level Input Voltage	$V_{Out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{Out} \le 20 \mu\text{A}$	2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	1.5 2.1 3.15 4.2	V
VIL	Maximum Low–Level Input Voltage	$V_{Out} = 0.1 \text{ V or } V_{CC} - 0.1 \text{ V}$ $ I_{Out} \le 20 \mu\text{A}$	2.0 3.0 4.5 6.0	0.5 0.9 1.35 1.80	0.5 0.9 1.35 1.80	0.5 0.9 1.35 1.80	V
VOH	Minimum High–Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \mu\text{A}$	2.0 4.5 6.0	1.9 4.4 5.9	1.9 4.4 5.9	1.9 4.4 5.9	V
		$\label{eq:Vin} \begin{split} V_{in} = V_{IH} \text{ or } V_{IL} & I_{out} \leq 2.4 \text{ mA} \\ & I_{out} \leq 4.0 \text{ mA} \\ & I_{out} \leq 5.2 \text{ mA} \end{split}$	3.0 4.5 6.0	2.48 3.98 5.48	2.34 3.84 5.34	2.20 3.70 5.20	V

^{*}Maximum Ratings are those values beyond which damage to the device may occur.

DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

				Guaranteed Limit			
Symbol	Parameter	Test Conditions	V _{CC}	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
V _{OL}	Maximum Low–Level Output Voltage	$V_{in} = V_{IH} \text{ or } V_{IL}$ $ I_{out} \le 20 \ \mu\text{A}$	2.0 4.5 6.0	0.1 0.1 0.1	0.1 0.1 0.1	0.1 0.1 0.1	V
		$\begin{aligned} \text{V}_{\text{in}} = \text{V}_{\text{IH}} \text{ or V}_{\text{IL}} & \text{I}_{\text{Out}} \leq 2.4 \text{ mA} \\ \text{I}_{\text{Out}} \leq 4.0 \text{ mA} \\ \text{I}_{\text{Out}} \leq 5.2 \text{ mA} \end{aligned}$	3.0 4.5 6.0	0.26 0.26 0.26	0.33 0.33 0.33	0.40 0.40 0.40	
l _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	6.0	± 0.1	± 1.0	± 1.0	μА
lcc	Maximum Quiescent Supply Current (per Package)	V _{in} = V _{CC} or GND I _{out} = 0 µA	6.0	4	40	160	μА

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

AC ELECTRICAL CHARACTERISTICS ($C_L = 50 \text{ pF}$, Input $t_f = t_f = 6 \text{ ns}$)

			Guaranteed Limit			
Symbol	Parameter	V _{CC}	– 55 to 25°C	≤ 85°C	≤ 125°C	Unit
fmax	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 8)	2.0 3.0 4.5 6.0	6 18 30 35	4.8 17 24 28	4 15 20 24	MHz
tPLH, tPHL	Maximum Propagation Delay, Clock (or Clock Inhibit) to ${\rm Q_H}$ or ${\rm \overline{Q}_H}$ (Figures 1 and 8)	2.0 3.0 4.5 6.0	150 52 30 26	190 63 38 33	225 65 45 38	ns
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Serial Shift/Parallel Load to Q_H or \overline{Q}_H (Figures 2 and 8)	2.0 3.0 4.5 6.0	175 58 35 30	220 70 44 37	265 72 53 45	ns
tPLH, tPHL	Maximum Propagation Delay, Input H to Q _H or $\overline{\mathbb{Q}}_{H}$ (Figures 3 and 8)	2.0 3.0 4.5 6.0	150 52 30 26	190 63 38 33	225 65 45 38	ns
tTLH, tTHL	Maximum Output Transition Time, Any Output (Figures 1 and 8)	2.0 3.0 4.5 6.0	75 27 15 13	95 32 19 16	110 36 22 19	ns
C _{in}	Maximum Input Capacitance	_	10	10	10	pF

NOTES:

- 1. For propagation delays with loads other than 50 pF, see Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).
- 2. Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

ſ			Typical @ 25° C, $V_{CC} = 5.0 \text{ V}$	
	C_{PD}	Power Dissipation Capacitance (Per Package)*	40	pF

^{*} Used to determine the no–load dynamic power consumption: P_D = C_{PD} V_{CC}²f + I_{CC} V_{CC}. For load considerations, see Chapter 2 of the Motorola High–Speed CMOS Data Book (DL129/D).

TIMING REQUIREMENTS (Input $t_f = t_f = 6 \text{ ns}$)

			Guaranteed Limit		mit	
	_	VCC	– 55 to			
Symbol	Parameter	V	25°C	≤ 85°C	≤ 125°C	Unit
t _{su}	Minimum Setup Time, Parallel Data Inputs to Serial Shift/Parallel Load	2.0	75	95	110	ns
	(Figure 4)	3.0	30	40	55	
		4.5	15	19	22	
		6.0	13	16	19	
t _{su}	Minimum Setup Time, Input SA to Clock (or Clock Inhibit)	2.0	75	95	110	ns
	(Figure 5)	3.0	30	40	55	
		4.5	15	19	22	
		6.0	13	16	19	
t _{su}	Minimum Setup Time, Serial Shift/Parallel Load to Clock (or Clock	2.0	75	95	110	ns
Su	Inhibit)	3.0	30	40	55	
	(Figure 6)	4.5	15	19	22	
	(3 1)	6.0	13	16	19	
t _{su}	Minimum Setup Time, Clock to Clock Inhibit	2.0	75	95	110	ns
'Su	(Figure 7)	3.0	30	40	55	110
	(i.igaio i)	4.5	15	19	22	
		6.0	13	16	19	
th	Minimum Hold Time, Serial Shift/Parallel Load to Parallel Data Inputs	2.0	5	5	5	ns
๚	(Figure 4)	3.0	5	5	5	113
	(i iguic 4)	4.5	5	5	5	
		6.0	5	5	5	
+,	Minimum Hold Time, Clock (or Clock Inhibit) to Input SA	2.0	5	5	5	ns
th	(Figure 5)	3.0	5	5	5	115
	(Figure 3)	4.5	5	5	5	
		6.0	5	5	5	
+.	Minimum Hold Time, Clock (or Clock Inhibit) to Serial Shift/Parallel	2.0	5	5	5	ns
^t h	Load	3.0	5	5	5	115
	(Figure 6)	4.5	5	5	5	
	(rigule o)	6.0	5	5	5	
	Marine Branco Tree Oled to Oled Little					
trec	Minimum Recovery Time, Clock to Clock Inhibit	2.0	75	95	110	ns
	(Figure 7)	3.0	30	40	55 33	
		4.5 6.0	15 13	19 16	22 19	
	Mariness Dates Wildle Olevel (et Olevel 1979)					
t_W	Minimum Pulse Width, Clock (or Clock Inhibit)	2.0	70	90	100	ns
	(Figure 1)	3.0	27	32	36	
		4.5	15	19	22	
		6.0	13	16	19	
t_W	Minimum Pulse width, Serial Shift/Parallel Load	2.0	70	90	100	ns
	(Figure 2)	3.0	27	32	36	
		4.5	15	19	22	
		6.0	13	16	19	
t _r , t _f	Maximum Input Rise and Fall Times	2.0	1000	1000	1000	ns
	(Figure 1)	3.0	800	800	800	
		4.5	500	500	500	
		6.0	400	400	400	

NOTE: Information on typical parametric values can be found in Chapter 2 of the Motorola High-Speed CMOS Data Book (DL129/D).

PIN DESCRIPTIONS

INPUTS

A, B, C, D, E, F, G, H (Pins 11, 12, 13, 14, 3, 4, 5, 6)

Parallel Data inputs. Data on these inputs are asynchronously entered in parallel into the internal flip—flops when the Serial Shift/Parallel Load input is low.

SA (Pin 10)

Serial Data input. When the Serial Shift/Parallel Load input is high, data on this pin is serially entered into the first stage of the shift register with the rising edge of the Clock.

CONTROL INPUTS

Serial Shift/Parallel Load (Pin 1)

Data—entry control input. When a high level is applied to this pin, data at the Serial Data input (SA) are shifted into the register with the rising edge of the Clock. When a low level is applied to this pin, data at the Parallel Data inputs are asynchronously loaded into each of the eight internal stages.

Clock, Clock Inhibit (Pins 2, 15)

Clock inputs. These two clock inputs function identically. Either may be used as an active—high clock inhibit. However, to avoid double clocking, the inhibit input should go high only while the clock input is high.

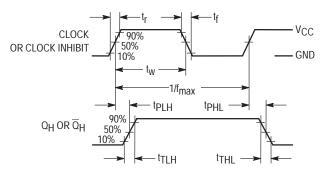
The shift register is completely static, allowing Clock rates down to DC in a continuous or intermittent mode.

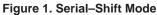
OUTPUTS

$Q_H, \overline{Q}_H (Pins 9, 7)$

Complementary Shift Register outputs. These pins are the noninverted and inverted outputs of the eighth stage of the shift register.

SWITCHING WAVEFORMS





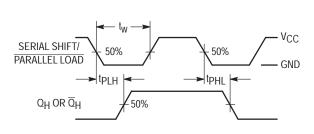


Figure 2. Parallel-Load Mode

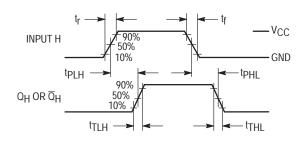


Figure 3. Parallel-Load Mode

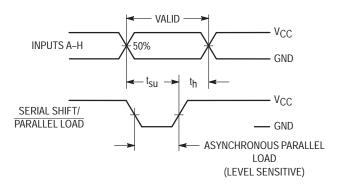


Figure 4. Parallel-Load Mode

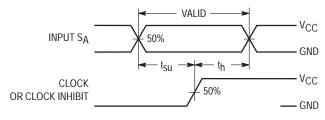


Figure 5. Serial-Shift Mode

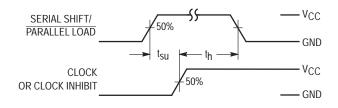


Figure 6. Serial-Shift Mode

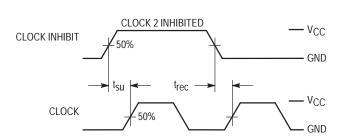
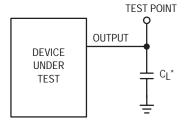


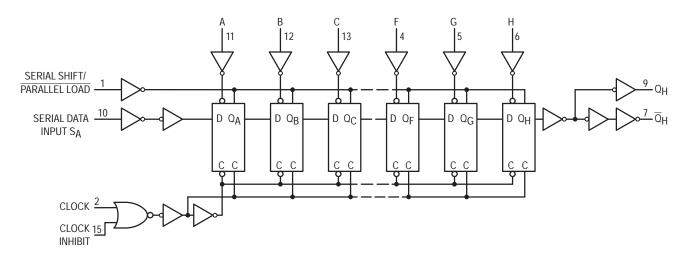
Figure 7. Serial-Shift, Clock-Inhibit Mode



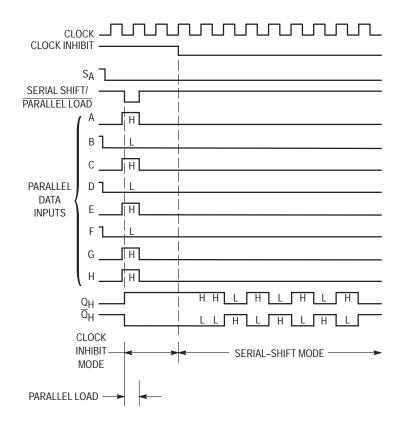
*Includes all probe and jig capacitance

Figure 8. Test Circuit

EXPANDED LOGIC DIAGRAM

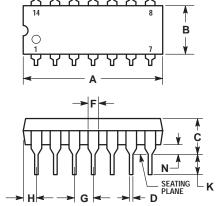


TIMING DIAGRAM



PACKAGE DIMENSIONS

PDIP-14 **N SUFFIX** CASE 646-06 ISSUE L



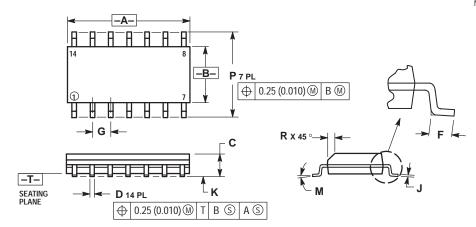


- NOTES:
 1. LEADS WITHIN 0.13 (0.005) RADIUS OF TRUE
 POSITION AT SEATING PLANE AT MAXIMUM
 MATERIAL CONDITION.
 2. DIMENSION L TO CENTER OF LEADS WHEN
 FORMED PARALLEL.
 3. DIMENSION B DOES NOT INCLUDE MOLD

 - FLASH.
 4. ROUNDED CORNERS OPTIONAL

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.715	0.770	18.16	19.56	
В	0.240	0.260	6.10	6.60	
С	0.145	0.185	3.69	4.69	
D	0.015	0.021	0.38	0.53	
F	0.040	0.070	1.02	1.78	
G	0.100	BSC	2.54	BSC	
Н	0.052	0.095	1.32	2.41	
J	0.008	0.015	0.20	0.38	
K	0.115	0.135	2.92	3.43	
L	0.300	BSC	7.62 BSC		
M	0°	10°	0°	10°	
N	0.015	0.039	0.39	1 01	

SOIC-14 **D SUFFIX** CASE 751A-03 ISSUE F



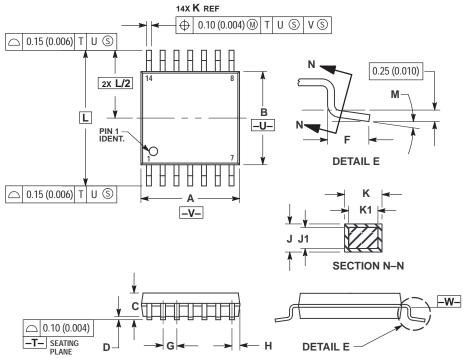
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI

- 1. DIMENSIONING AND TOLERANCING PER ANS Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWARD F. DAMBAR.
- PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	METERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	8.55	8.75	0.337	0.344
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27	BSC	0.050	BSC
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0 °	7°	0 °	7°
Р	5.80	6.20	0.228	0.244
R	0.25	0.50	0.010	0.019

PACKAGE DIMENSIONS

TSSOP-14 **DT SUFFIX** CASE 948G-01 **ISSUE O**



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15
- OR GATE BURRS SHALL NOT EXCEED 0.15
 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH OR
 PROTRUSION SHALL NOT EXCEED
 0.25 (0.010) PER SIDE.
 DIMENSION K DOES NOT INCLUDE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN
 EXCESS OF THE K DIMENSION AT MAXIMUM
 MATERIAL CONDITION. MATERIAL CONDITION.
 TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026	BSC	
Н	0.50	0.60	0.020	0.024	
J	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
K	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40		0.252 BSC		
M	0°	8°	0°	8°	

Notes

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